

1.8mm BI-LEVEL CIRCUIT BOARD INDICATOR

Part Number: WP4060VH/IGD

High Efficiency Red

Features

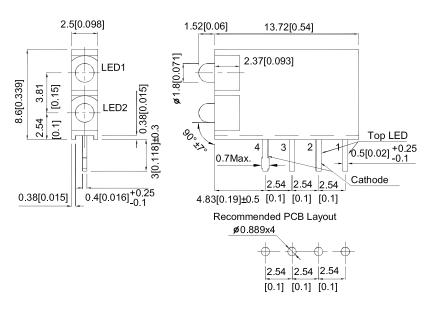
- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Descriptions

- The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.
- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions

LED 1: Red LED 2 : Green



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
 The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
	- , , ,		Min.	Тур.	201/2
WP4060VH/IGD	High Efficiency Red (GaAsP/GaP)	Red Diffused	8	15	70°
		Red Dillused	*4	*8	
	Green (GaP)	Green Diffused	6	12	70°
			*6	*12	

Notes:

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity / luminous Flux: +/-15%.
 Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Green	627 565		nm	Ir=10mA
λD [1]	Dominant Wavelength	High Efficiency Red Green	617 568		nm	I==10mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Green	45 30		nm	I==10mA
С	Capacitance	High Efficiency Red Green	15 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red Green	1.9 2	2.5 2.5	V	I==10mA
lr	Reverse Current	High Efficiency Red Green		10 10	uA	VR = 5V

Notes:

- 1. Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to CIE127-2007 standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

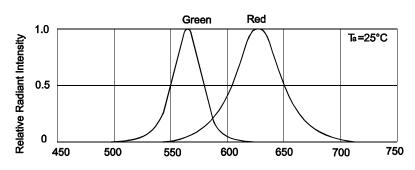
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Green	Units		
Power dissipation	75	62.5	mW		
DC Forward Current	30	25	mA		
Peak Forward Current [1]	160	140	mA		
Reverse Voltage		V			
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				

Notes:

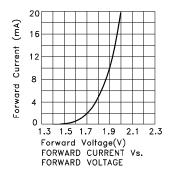
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.
- 3. 5mm below package base.
- 4. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

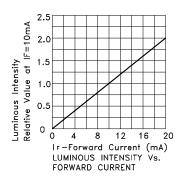
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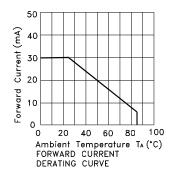


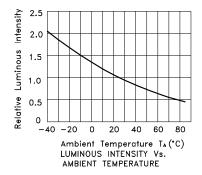
 $\mbox{ wavelength } \lambda \mbox{ (nm)} \\ \mbox{ Relative Intensity Vs. Wavelength} \\$

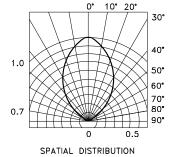
WP4060VH/IGD High Efficiency Red





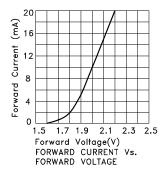


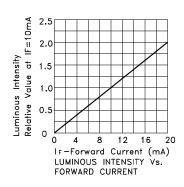


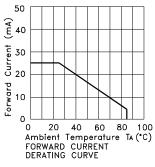


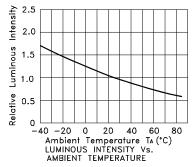
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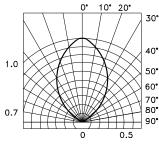
Green





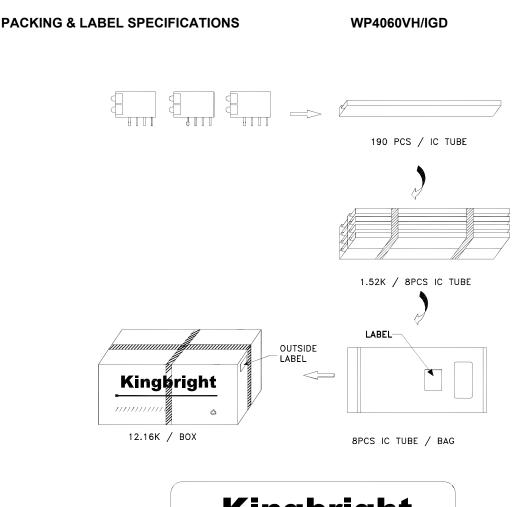






SPATIAL DISTRIBUTION

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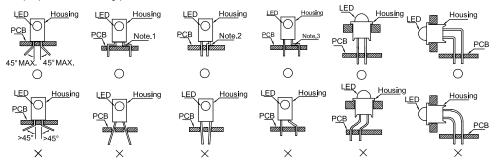
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PRECAUTIONS

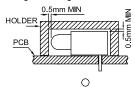
- 1. Storage conditions:
 - a. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
 - b.LEDs should be stored with temperature ≤ 30°C and relative humidity < 60%.
 - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (\pm 10/-0) hours at 85 ~ 100°C.
- The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

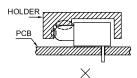


" \bigcirc " Correct mounting method " imes " Incorrect mounting method

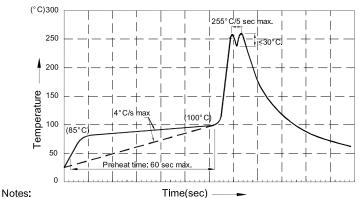
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.





- 4. The tip of the soldering iron should never touch the lens epoxy.
- 5. Through-hole LEDs are incompatible with reflow soldering.
- If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245° C ~ 255° C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4. Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6 No more than one wave soldering pass.

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